



## Material Content Data Sheet



<b>Sales Product Name</b>		TDA5201		<b>Issued</b>		7. September 2015		
<b>MA#</b>		MA000225807						
<b>Package</b>		PG-TSSOP-28-1		<b>Weight*</b>		106.95 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.077	1.94	1.94	19418	19418
leadframe	non noble metal	nickel	7440-02-0	14.398	13.46		134620	
	non noble metal	iron	7439-89-6	19.882	18.59	32.05	185904	320524
wire	noble metal	gold	7440-57-5	0.984	0.92	0.92	9197	9197
encapsulation	organic material	carbon black	1333-86-4	0.197	0.18		1844	
	plastics	epoxy resin	-	8.348	7.81		78051	
	inorganic material	silicondioxide	60676-86-0	57.184	53.47	61.46	534684	614579
leadfinish	non noble metal	tin	7440-31-5	1.559	1.46	1.46	14574	14574
plating	noble metal	silver	7440-22-4	1.416	1.32	1.32	13237	13237
glue	plastics	acrylic resin	-	0.181	0.17		1694	
	noble metal	silver	7440-22-4	0.725	0.68	0.85	6777	8471
*deviation	< 10%			Sum in total:		100.00		1000000

### Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com